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(12) **United States Design Patent**
Wang

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(54) **HEADPHONE**

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(**) Term: **14 Years**

(21) Appl. No.: **29/277,874**

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(51) **LOC (8) Cl.** **14-01**
(52) **U.S. Cl.** **D14/206**
(58) **Field of Classification Search** D14/188, D14/192, 205–206, 223; D29/112; 2/209.3, 2/410; 181/129–130; 381/370–371, 374, 381/376, 377–379; 379/430, 440, 433.01; D21/483, 516–517; 455/565, 575.2; 29/594
See application file for complete search history.

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Primary Examiner—Paula A. Greene

(57) **CLAIM**

The ornamental design for a headphone, as shown.

DESCRIPTION

FIG. **1** is a front elevational view of a headphone showing my new design;

FIG. **2** is a rear elevational view thereof;

FIG. **3** is a left side view thereof;

FIG. **4** is a right side view thereof;

FIG. **5** is a top plan view thereof;

FIG. **6** is a bottom plan view thereof; and,

FIG. **7** is a perspective view thereof.

1 Claim, 5 Drawing Sheets

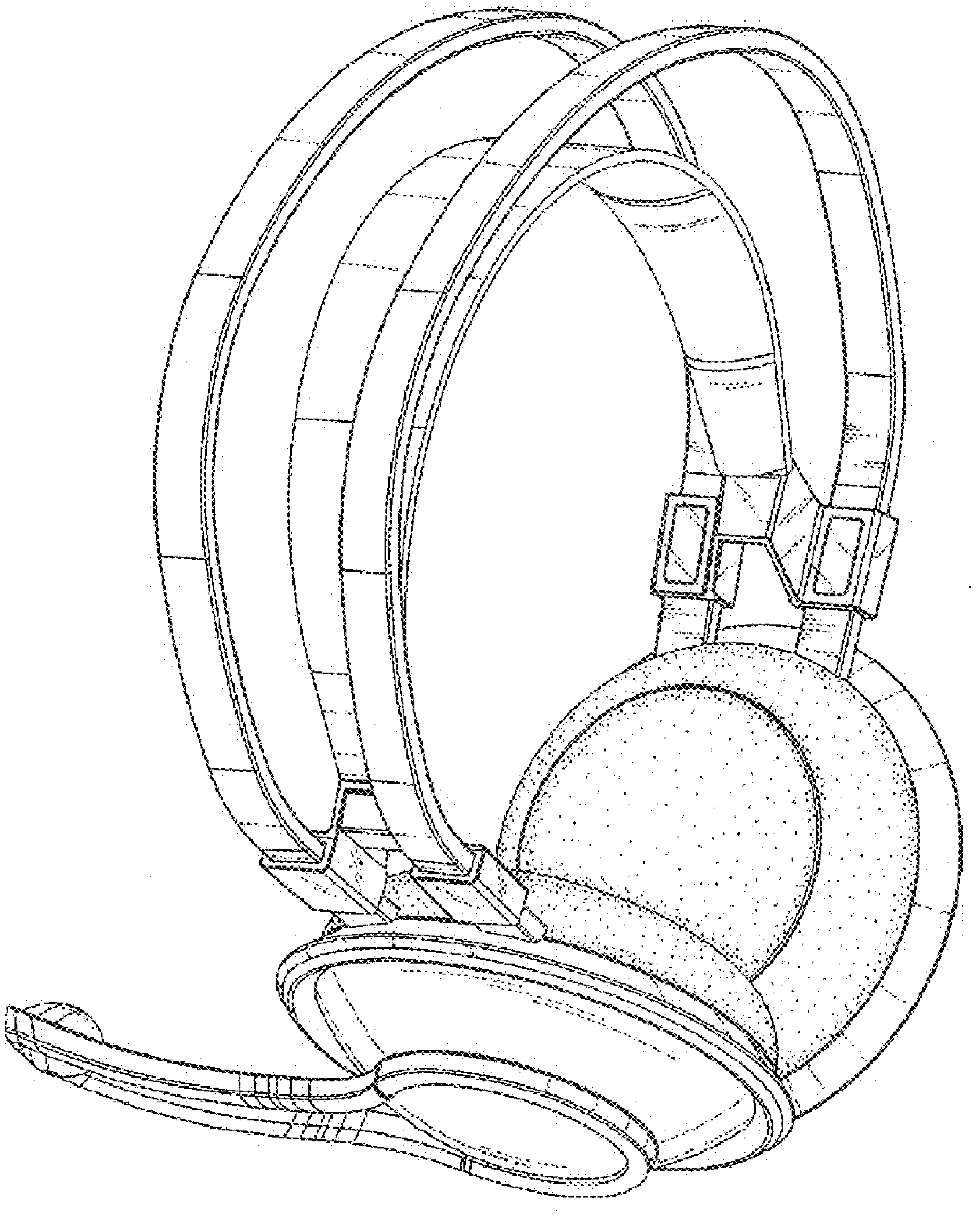

Fig. 1

Fig. 2

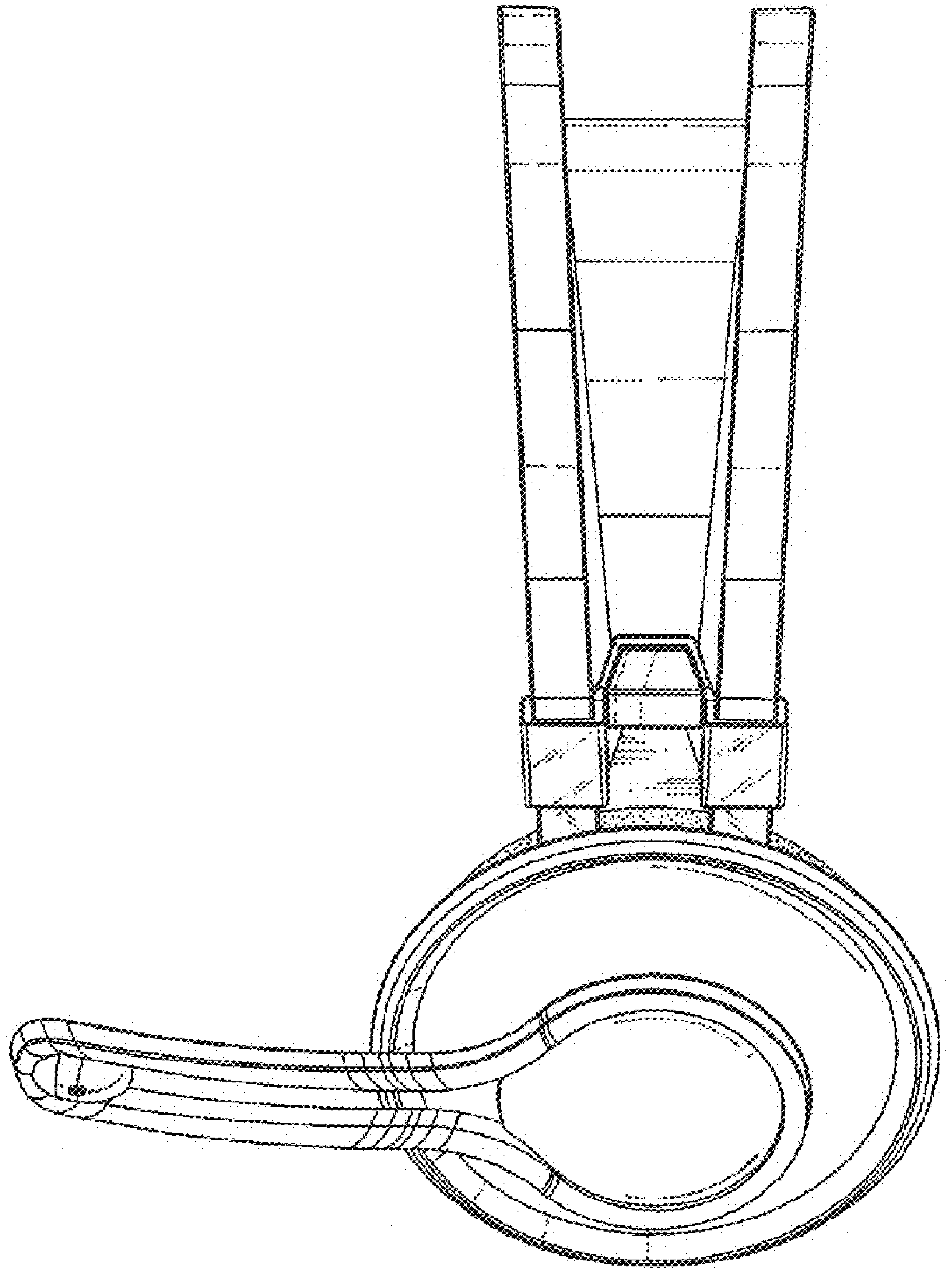

Fig. 3

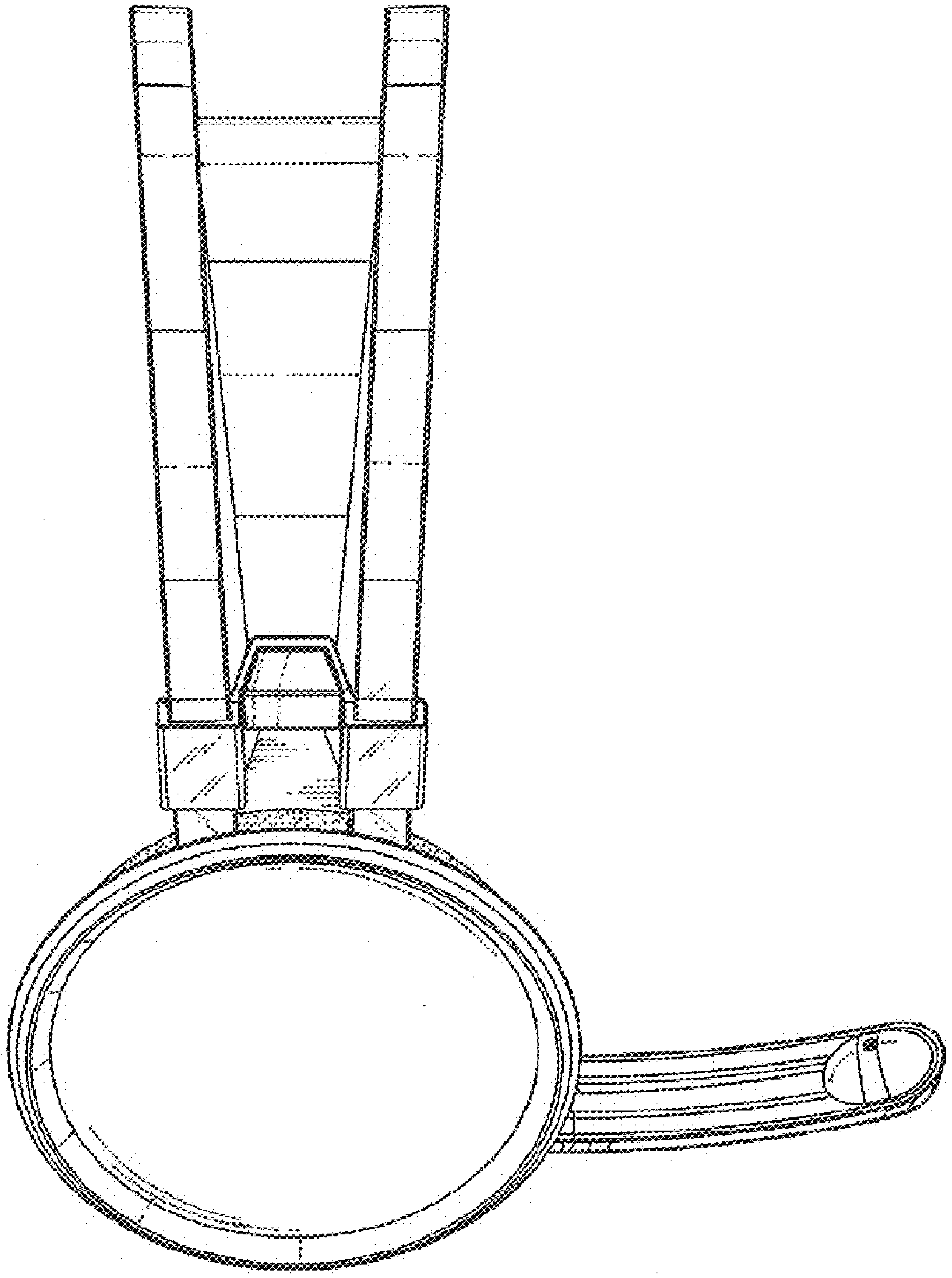

Fig. 4

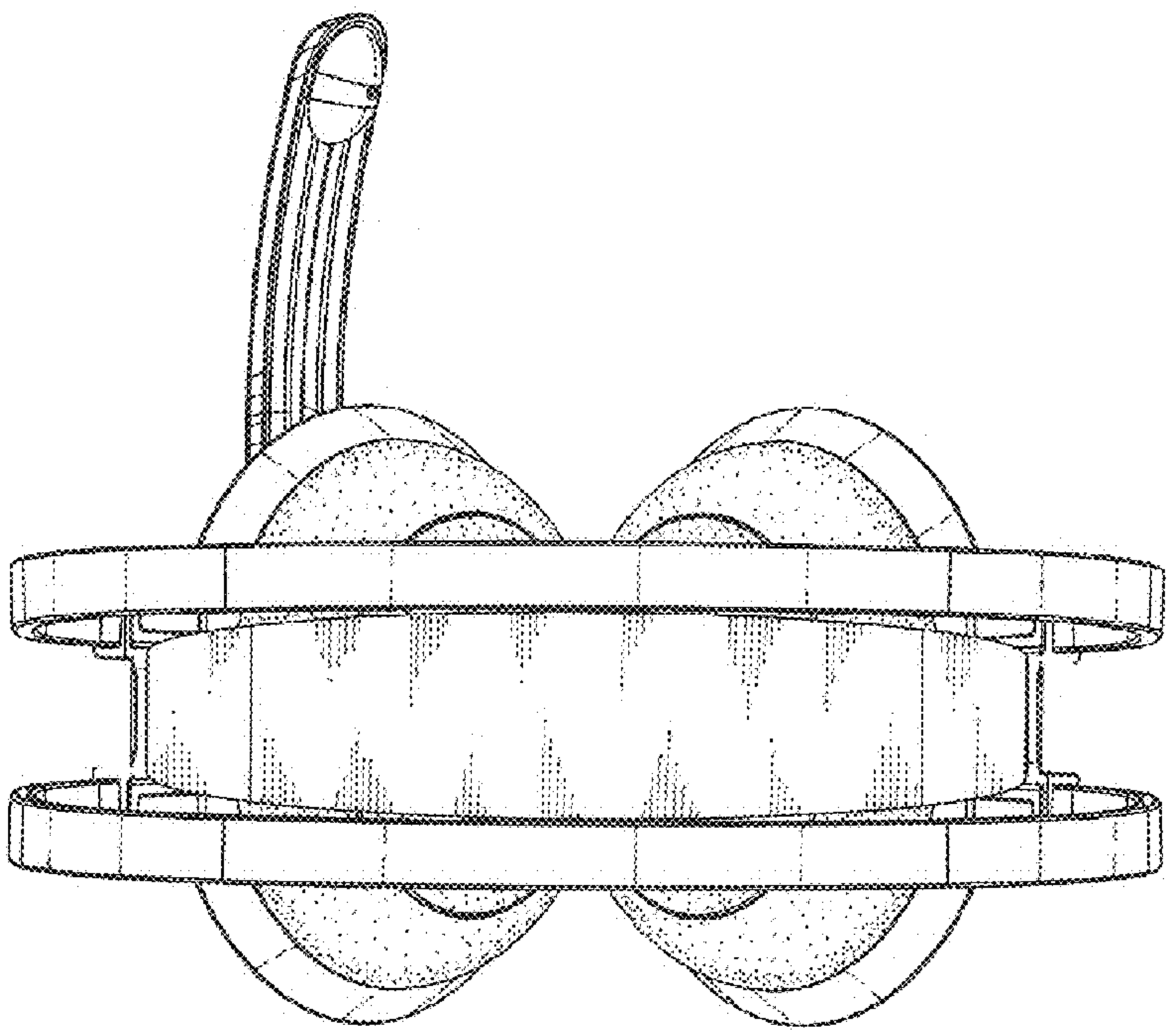

Fig. 5

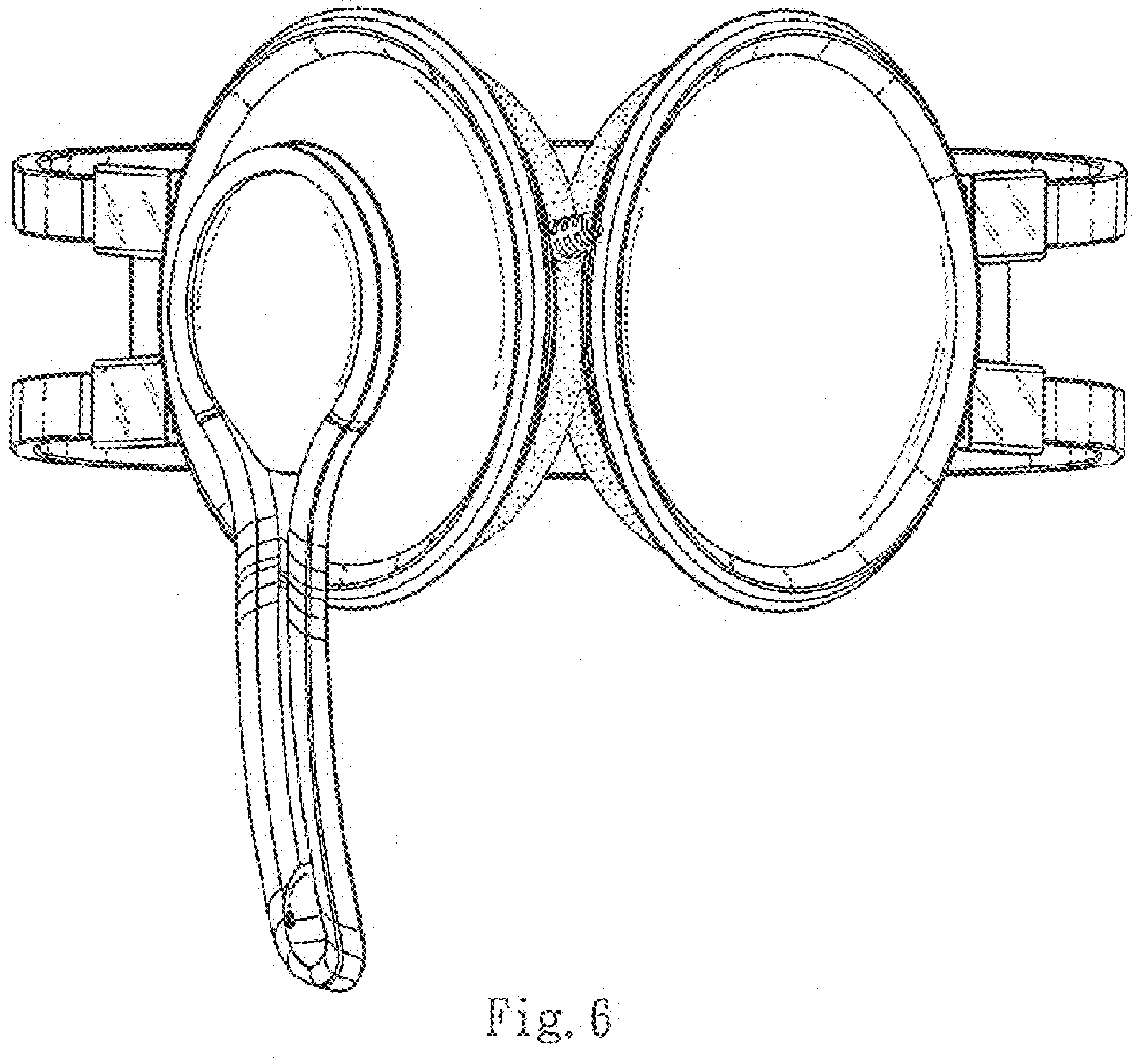

Fig. 6

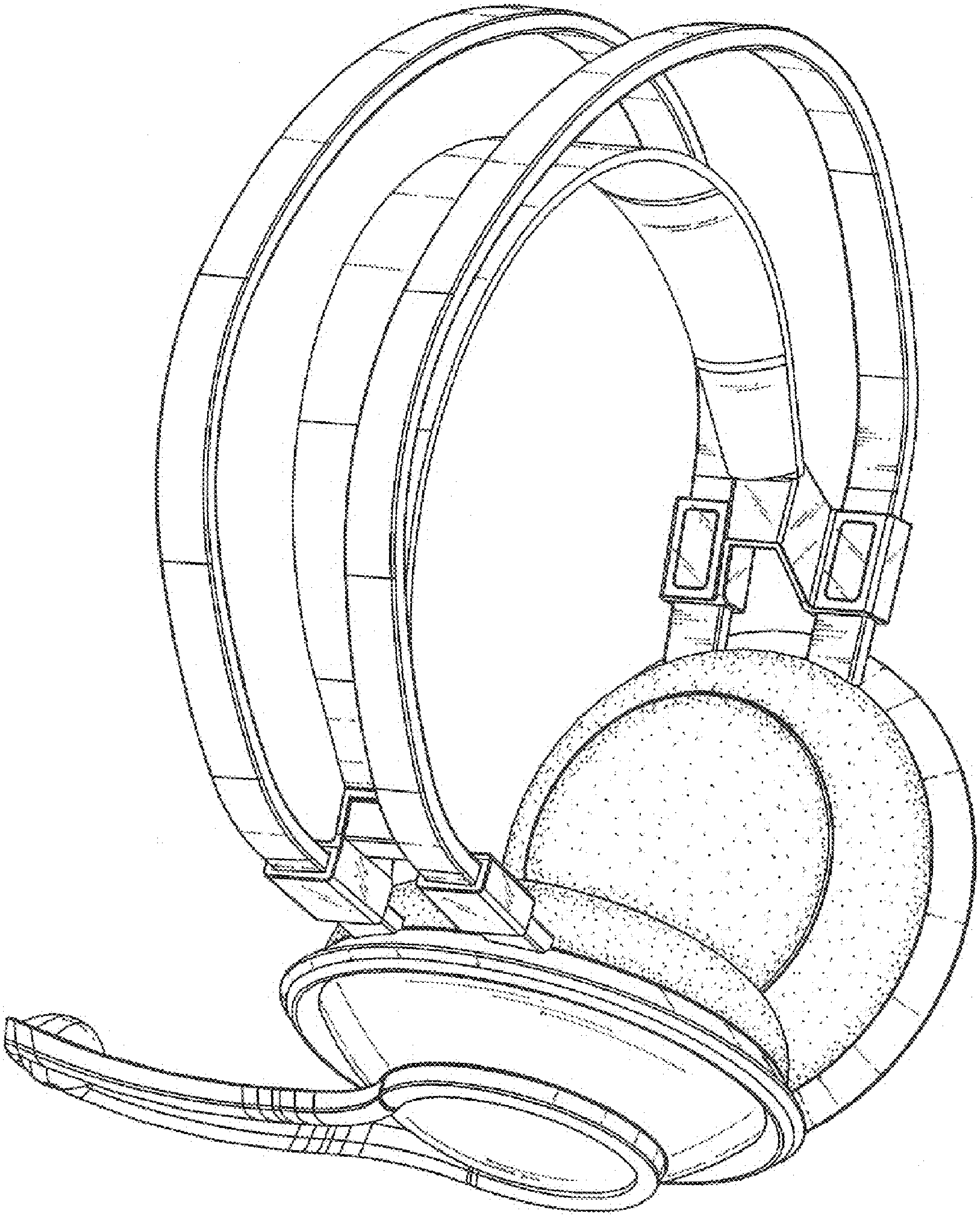

Fig. 7